## **PMP7772**

**PMP7772 BOM** 



Literature Number:SNVR044

## **Bill of Materials Report**

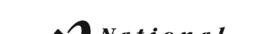
Project Name: 66mm Power Supply
Project File: NSC0966.PrjPCB

Variant: None

Schematic Rev: 1

Creation Date: 10/6/2008 10:58:51 AM

Print Date: 10/6/2008 2:05:12 PM



**Document P/N: 980xxxxxx** 



Designator	CompType	Value	Footprint	Parameters	Manufacturer	Manufacturer_PN
C100	Capacitor	2.2uF	1210	, , 50VV, %	TDK	C3225X7R1H225K
C101	Capacitor	2.2uF	1210	, , 50VV, %	TDK	C3225X7R1H225K
C102	Capacitor	0.47uF	0805	Ceramic, X7R, 25V, 10%	TDK	C2012X7R1E474K
C103	Capacitor	470pF	0805	Ceramic, C0G/NP0, 25V, 5%	Kemet	C0805C471CJ3GAC
C104	Capacitor	0.01uF	0805	Ceramic, C0G/NP0, 25V, 5%	TDK	C2012C0G1E103J
C105	Capacitor	0.022uF	0805	Ceramic, X7R, 100V, 10%	TDK	C2012X7R2A223K
C106	Capacitor	open	0805	, , V, %		
C107	Capacitor	2200pF	0805	Ceramic, X7R, 100V, 10%	TDK	C2012X7R2A222K
C108	Capacitor	open	0805	, , V, %		
C110	Capacitor	22uF	1210	, , 25VV, %	Murata	GRM32ER61E226KE15L
C111	Capacitor	22uF	1210	, , 25VV, %	Murata	GRM32ER61E226KE15L
C112	Capacitor	22uF	1210	, , 25VV, %	Murata	GRM32ER61E226KE15L
C113	Capacitor	22uF	1210	, , 25VV, %	Murata	GRM32ER61E226KE15L
C114	Capacitor	22uF	1210	, , 25VV, %	Murata	GRM32ER61E226KE15L
D100	Diode	60V	SMC	Vr = 60VV, $Io = A$ , $Vf = V$	Central Semiconductor	CMSH30-60
L100	Inductor	47uH	MSS1260	Shielded Drum Core, 2.6A, 0.10hm	Coilcraft Inc.	MSS1260-473MLB
R100	Resistor	21.0k	0805	1%, 0.125W	Vishay-Dale	CRCW080521k0FKEA
R101	Resistor	16.9k	0805	1%, 0.125W	Vishay-Dale	CRCW080516k9FKEA
R102	Resistor	1.65k	0805	1%, 0.125W	Vishay-Dale	CRCW08051k65FKEA
R103	Resistor	6.34k	0805	1%, 0.125W	Vishay-Dale	CRCW08056k34FKEA
R104	Resistor	200k	0805	1%, 0.125W	Vishay-Dale	CRCW0805200kFKEA
R106	Resistor	open	1206	%, W		
R110	Resistor	1.50k	1206	1%, 0.25W	Vishay-Dale	CRCW12061k50FKEA
U100	Switcher		MXA16A		National Semiconductor	LM25575MH

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